## Chip Beads HF30ACC321611-T

Applications	Com	nmercial Grade
Feature	Signal Sign	al Line
Series	HFxxACC Series / HFxxACC3216 Type	
Status	Production	



Size			
Length(L)	3.20mm +/-0.20mm		
Width(W)	1.60mm +/-0.20mm		
Thickness(T)	1.10mm +/-0.20mm		
Recommended Land Pattern (A)	1.10mm Nom.		
Recommended Land Pattern (B)	2.20mm Nom.		
Recommended Land Pattern (C)	1.40mm Nom.		

Electrical Characteristics			
Impedance at 100MHz	19Ω +/-25%		
Rated Current	1.5A		
DC Resistance [Max.]	40mΩ		

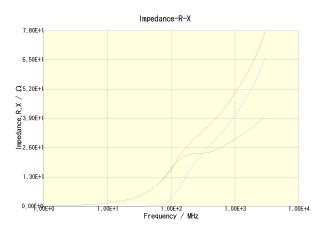
Other				
Operating Temp. Range (Including Self-Temp. Rise)	-40 to 125degC			
Soldering Method	Reflow, Iron Soldering			
AEC Q200	No			
Packing	Blister (Plastic)Taping [180mm Reel]			
Package Quantity	2000Pcs Min.			
Weight	0.022g			

•This PDF document was created based on the data listed on the TDK Corporation website.

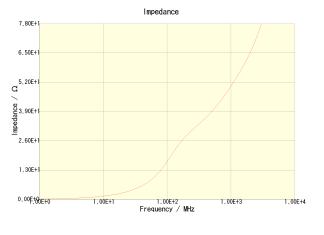
•All specifications are subject to change without notice.

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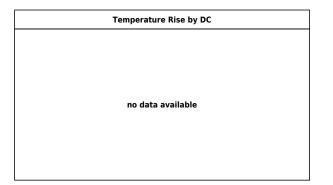
Characteristic Graphs (This is reference data, and does not guarantee the product's characteristics.)



HF30ACC321611-T(|Z|) HF30ACC321611-T(R) HF30ACC321611-T(X)



HF30ACC321611-T



Derating
no data available

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